

MATERIAL DECLARATION SHEET



Material Number	FPM Series			
Product Line	Fixed Resistors			
Compliance Date	2025/7/15			
RoHS Compliant	Yes	MSL	1	

Reference part number: FPM3254

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Plating	2.64	Tin	7440-31-5	90.9	0.025	0.027
				Copper	7440-50-8	7.6	0.002	
				Silver	7440-22-4	1.5	0	
2	Leads	Copper	590	Copper	7440-50-8	100	6.084	6.084
3	Inside Soldering	Tin Plating	10.56	Tin	7440-31-5	90.9	0.099	0.109
				Copper	7440-50-8	7.6	0.008	
				Silver	7440-22-4	1.5	0.002	
4	Heatsink	Aluminum Anodized	4570	Aluminum	7429-90-5	100	47.127	47.127
5	Chipbond	Filled Epoxy	200	Epoxy	25068-38-6	100	2.062	2.062
6	Substrate	Aluminum	570	Aluminum	7429-90-5	100	5.878	5.878

MATERIAL DECLARATION SHEET



7	Foildbond	Foildbond	50	Dimethylacetamid e	127-19-5	100	0.516	0.516
8	Resistor Material	Manganin ^{R1}	500	Copper	7440-50-8	83	4.28	5.157
				Nickel	7440-02-0	3	0.155	
				Manganese	7439-96-5	14	0.722	
9	Cover	Silicone Based	4	Silicon	7440-21-3	100	0.041	0.041
10	Mold	Epoxy	3200	Epoxy Black	68928-70-1	100	32.999	32.999
		Total weight	9697.2					

This Document was updated on: 2025/7/15

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.